

Lecture 2: ARM Processor Example

Outline

- Design Partitioning
- ARM Processor Example
 - Architecture
 - Microarchitecture
 - Logic Design
 - Circuit Design
 - Physical Design
- Fabrication, Packaging, Testing

Activity 2

- Sketch a stick diagram for a 4-input NOR gate

Coping with Complexity

- How to design System-on-Chip?
 - Many millions (even billions!) of transistors
 - Tens to hundreds of engineers
- Structured Design
- Design Partitioning

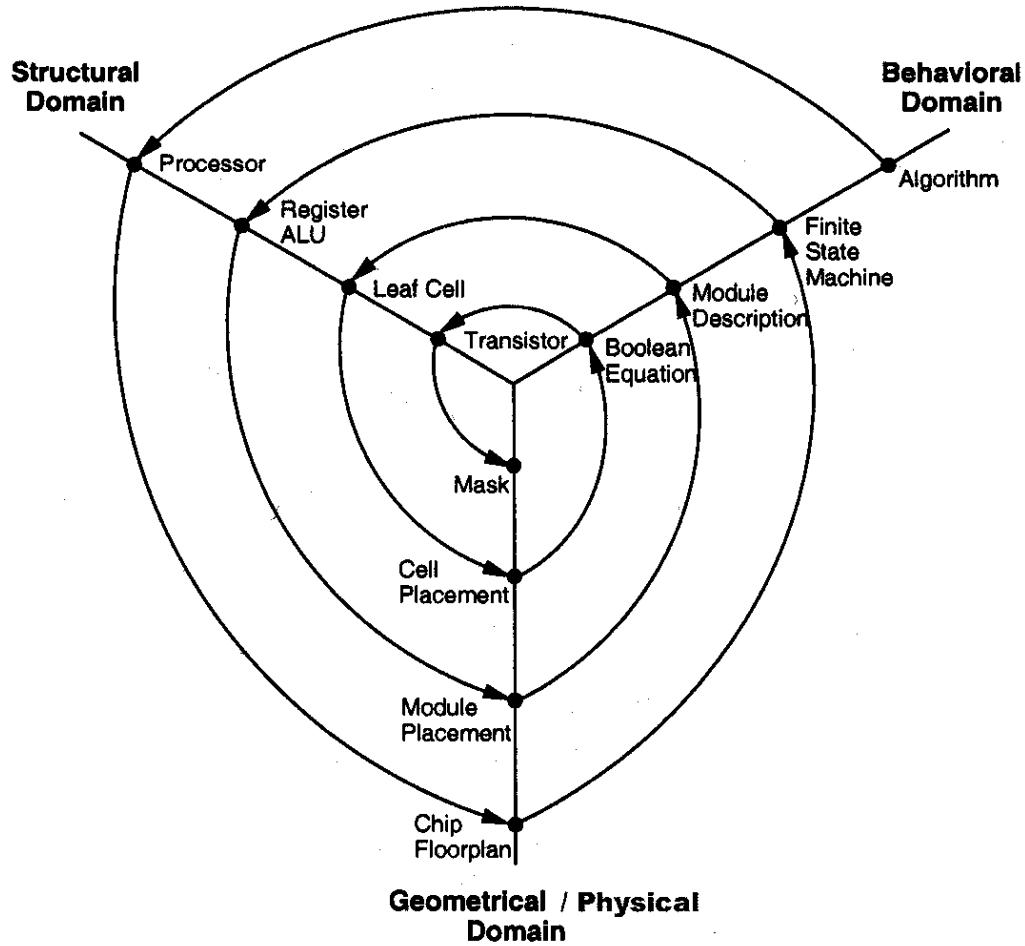
Structured Design

- **Hierarchy:** Divide and Conquer
 - Recursively system into modules
- **Regularity**
 - Reuse modules wherever possible
 - Ex: Standard cell library
- **Modularity:** well-formed interfaces
 - Allows modules to be treated as black boxes
- **Locality**
 - Physical and temporal

Design Partitioning

- **Architecture:** User's perspective, what does it do?
 - Instruction set, registers
 - ARM, MIPS, x86, Alpha, PIC, RISC-V, ...
 - **Microarchitecture**
 - Single cycle, multicycle, pipelined, superscalar?
 - **Logic:** how are functional blocks constructed
 - Ripple carry, carry lookahead, carry select adders
 - **Circuit:** how are transistors used
 - Complementary CMOS, pass transistors, domino
 - **Physical:** chip layout
 - Datapaths, memories, random logic
-

Gajski Y-Chart



ARM Architecture

- Example: subset of ARM processor architecture
 - Drawn from DDCA ARM Ed. (Harris & Harris)
- ARM is a 32-bit architecture with 16 registers
 - Consider 8-bit subset using 8-bit datapath
 - Only implement 8 registers (R0 - R7)
 - 8-bit program counter in R7
- You'll build this processor in the labs
 - Illustrate the key concepts in VLSI design

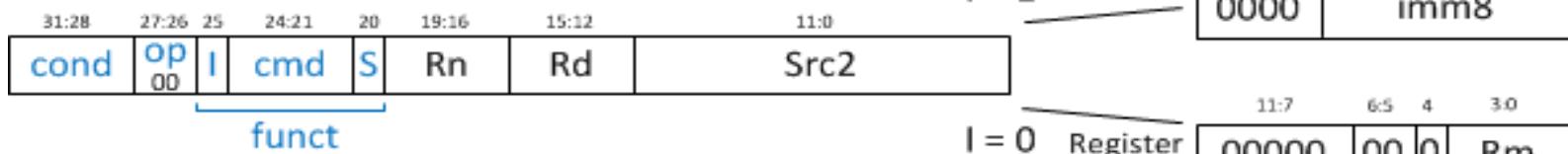
Instruction Set

- Data Processing
 - ADD, SUB, AND, OR
 - Each accepts register / immediate 2nd sources
- Memory
 - LDR, STR
 - Positive immediate offset
- Branch
 - B

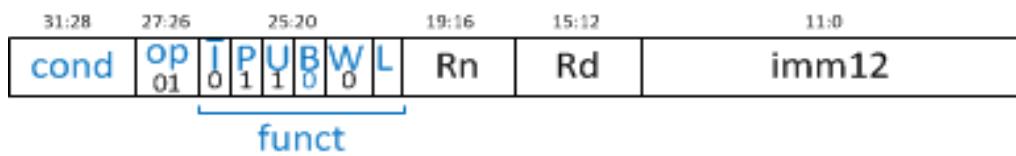
Instruction Encoding

- 32-bit instruction encoding
 - Requires four cycles to fetch on 8-bit datapath

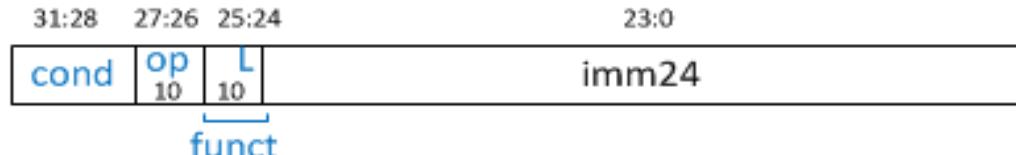
Data-processing



Memory



Branch



I = 1 Immediate	I = 0 Register
11:8 0000	11:7 00000
7:0 imm8	6:5 00

cmd	instr
0100	ADD
0010	SUB
0000	AND
1100	OR

Fibonacci (C)

$$f_0 = 1; f_{-1} = -1$$

$$f_n = f_{n-1} + f_{n-2}$$

$$f = 1, 1, 2, 3, 5, 8, 13, \dots$$

```
int fib(void)
{
    int n = 8;           /* compute nth Fibonacci number */
    int f1 = 1, f2 = -1; /* last two Fibonacci numbers */

    while (n != 0) {     /* count down to n = 0 */
        f1 = f1 + f2;
        f2 = f1 - f2;
        n = n - 1;
    }
    return f1;
}
```

Fibonacci (Assembly)

```
# fib.asm
# Register usage: R0 = 0, R3 = n, R4 = f1, R5 = f2
# Put result in address 255

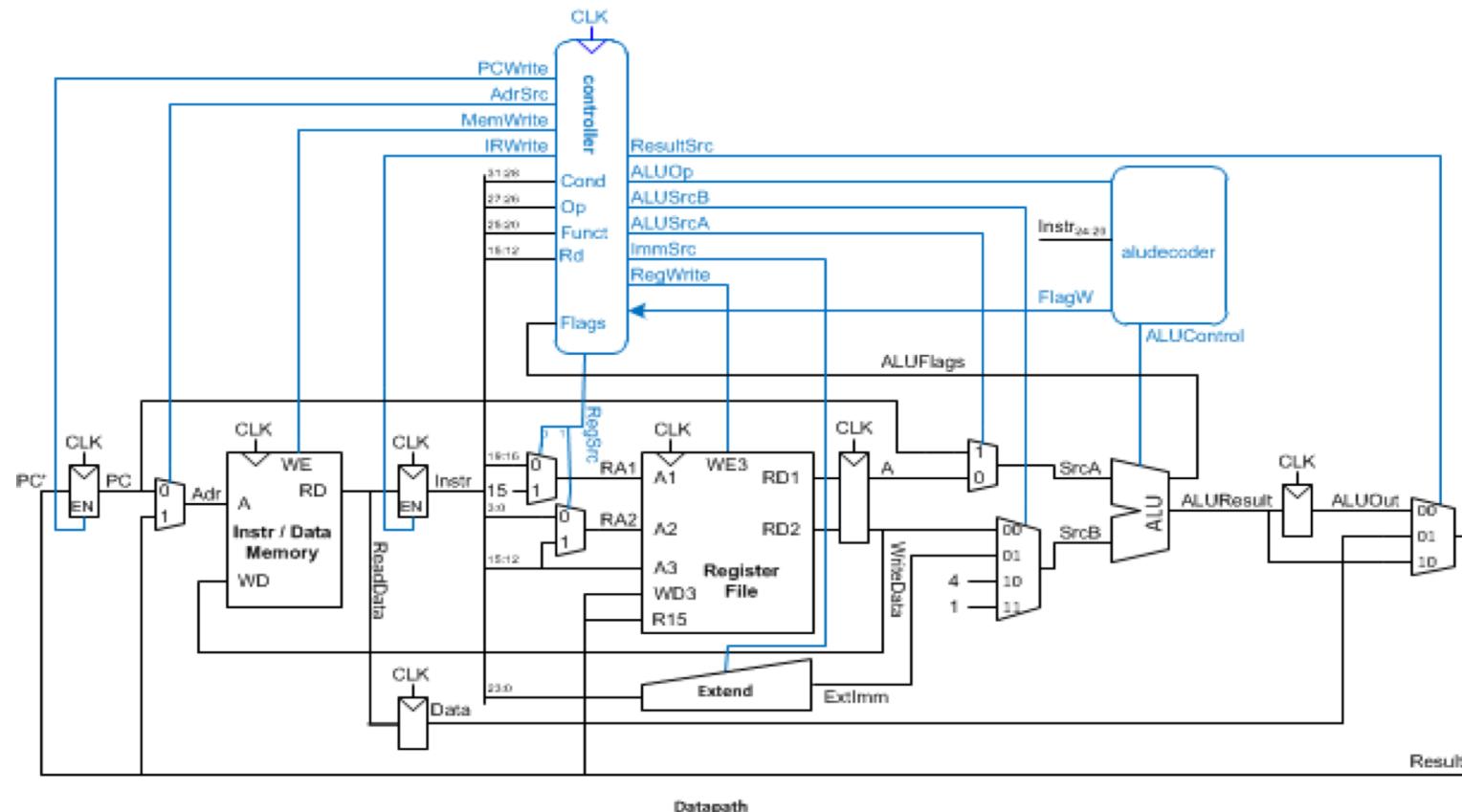
fib    add R3, R0, #8          # initialize n = 8
       add R4, R0, #1          # initialize f1 = 1
       add R5, R0, #-1         # initialize f2 = -1

loop   subs R3, R0, end       # n = 0?
       beq done                # then done
       add R4, R4, R5          # f1 = f1 + f2
       sub R5, R4, R5          # f2 = f1 – f2
       add R3, R3, #-1         # n = n-1
       b loop                 # repeat until done

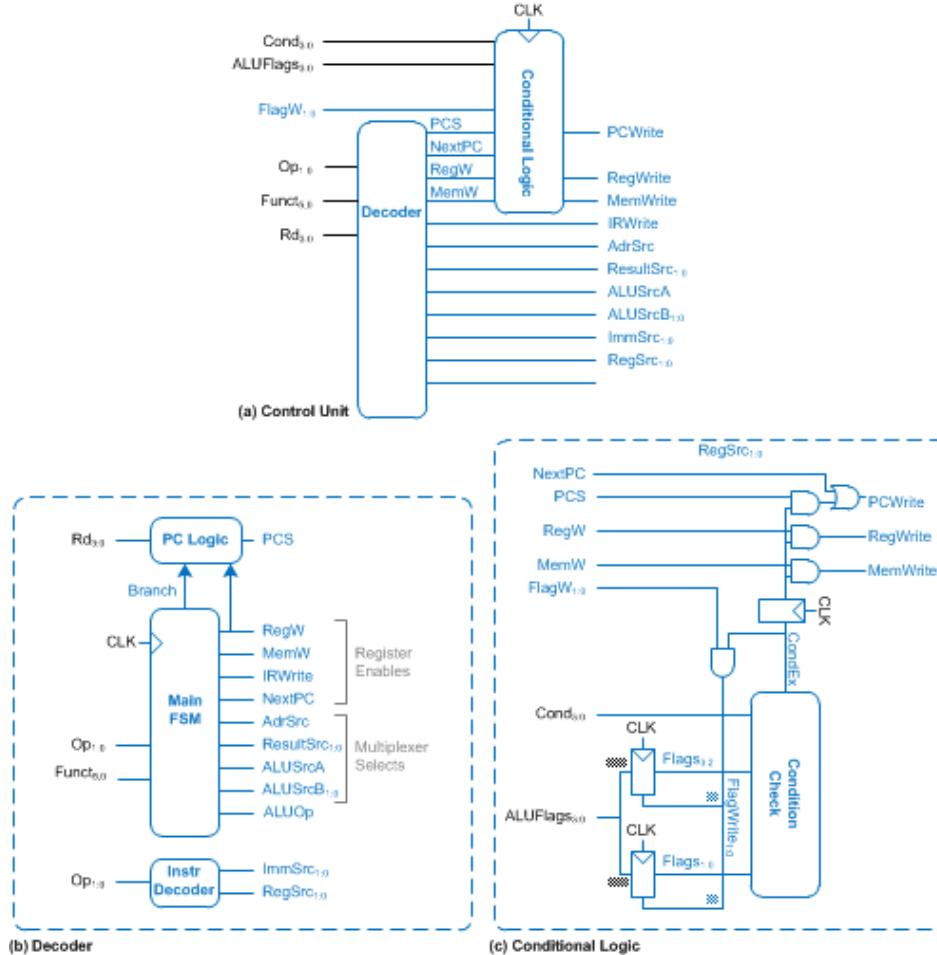
done   str R4, [R0, #255]     # store result in adr 255
```

ARM Microarchitecture

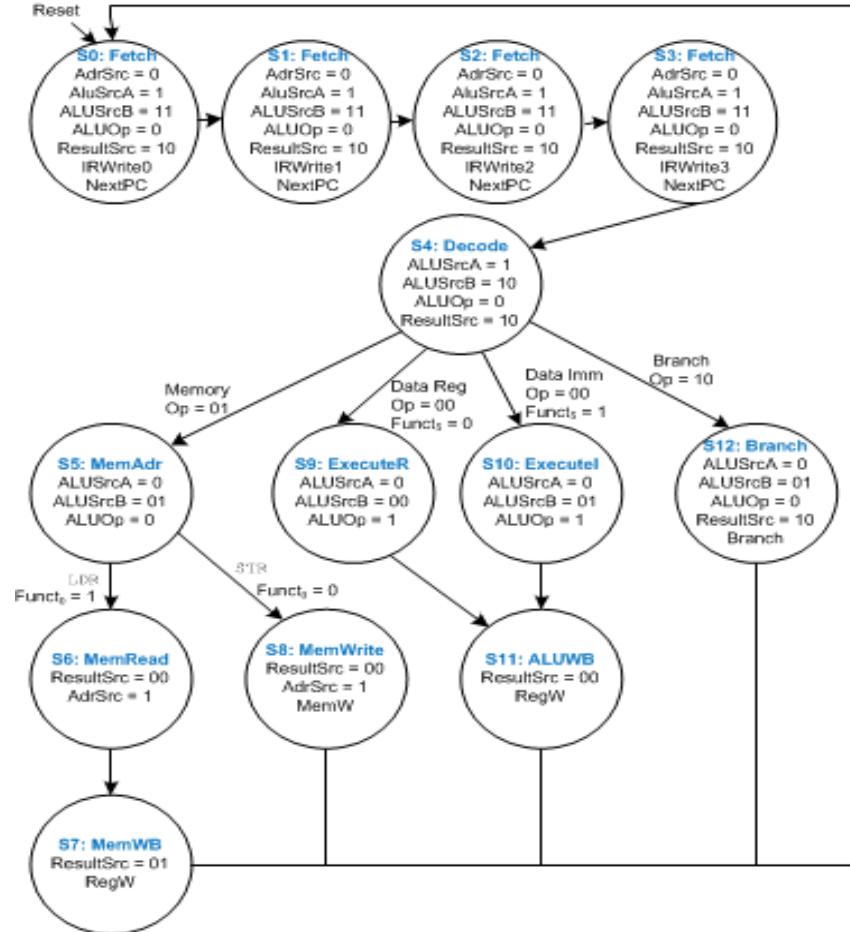
- Multicycle µarchitecture (Harris DDCA ARM Ed.)



Multicycle Controller

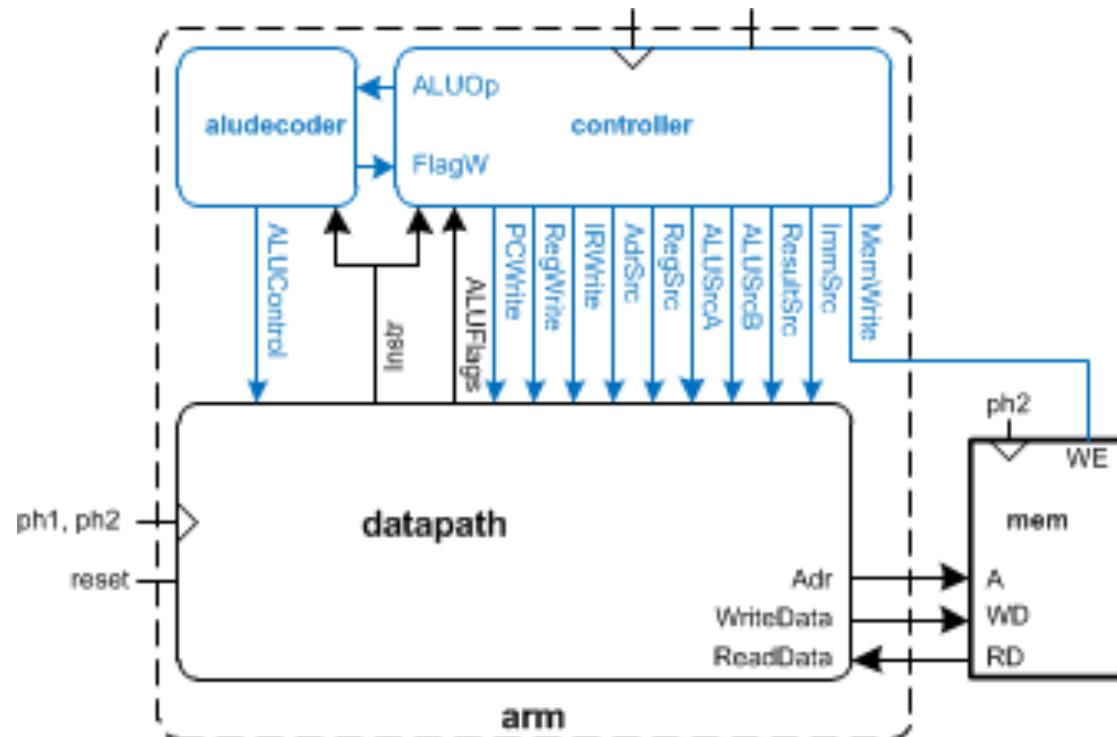


Multicycle FSM

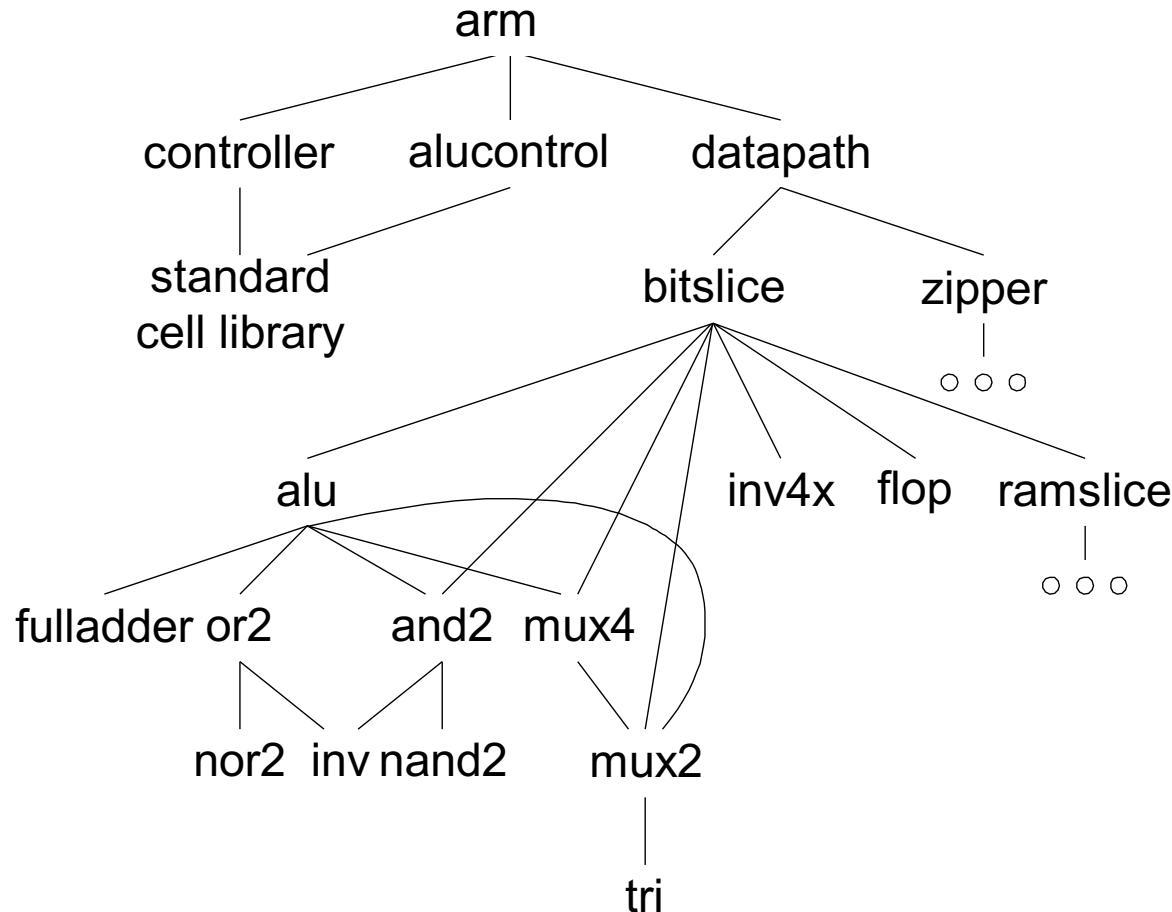


Logic Design

- Start at top level
 - Hierarchically decompose ARM into units



Hierarchical Design



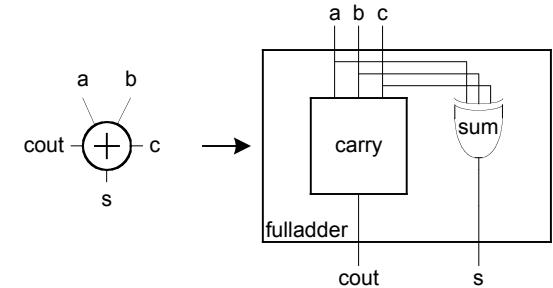
HDLs



- Hardware Description Languages
 - Widely used in logic design
 - Verilog and VHDL
- Describe hardware using code
 - Document logic functions
 - Simulate logic before building
 - Synthesize code into gates and layout
 - Requires a library of standard cells

Verilog Example

```
module fulladder(input a, b, c,
                  output s, cout);
    sum      s1(a, b, c, s);
    carry    c1(a, b, c, cout);
endmodule
```



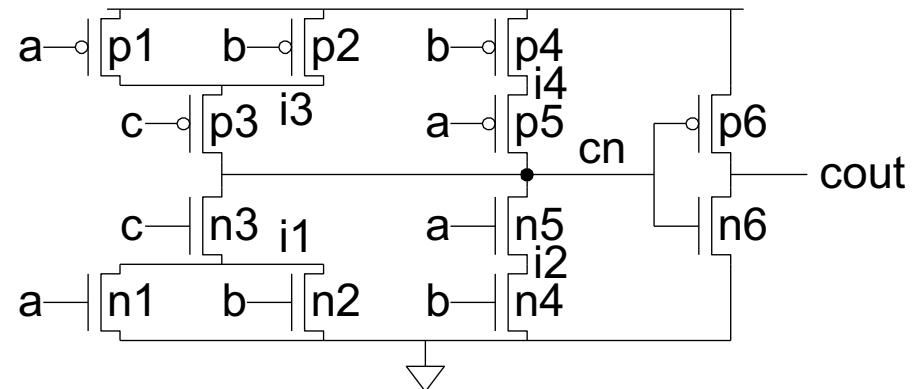
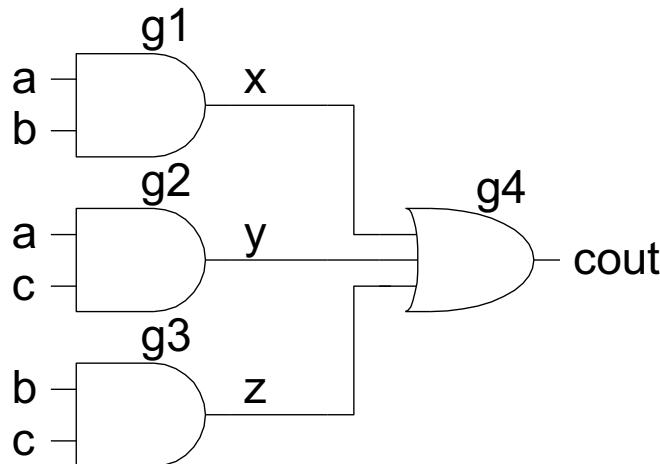
```
module carry(input a, b, c,
              output cout)
    assign cout = (a&b) | (a&c) | (b&c);
endmodule
```

Circuit Design

- How should logic be implemented?
 - NANDs and NORs vs. ANDs and ORs?
 - Fan-in and fan-out?
 - How wide should transistors be?
- These choices affect speed, area, power
- Logic synthesis makes these choices for you
 - Good enough for many applications
 - Hand-crafted circuits are still better

Example: Carry Logic

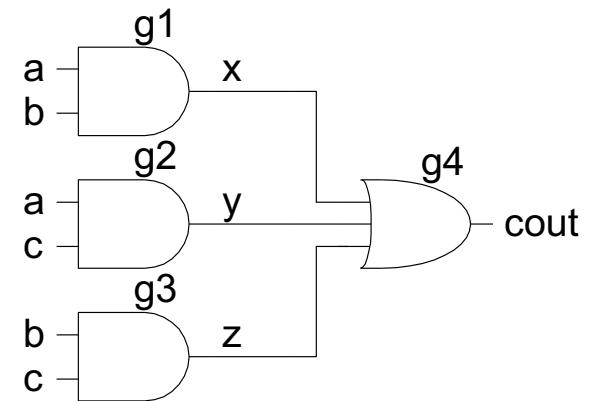
☐ **assign** cout = (a&b) | (a&c) | (b&c) ;



Transistors? Gate Delays?

Gate-level Netlist

```
module carry(input a, b, c,  
             output cout)  
  
    wire x, y, z;  
  
    and g1(x, a, b);  
    and g2(y, a, c);  
    and g3(z, b, c);  
    or  g4(cout, x, y, z);  
  
endmodule
```



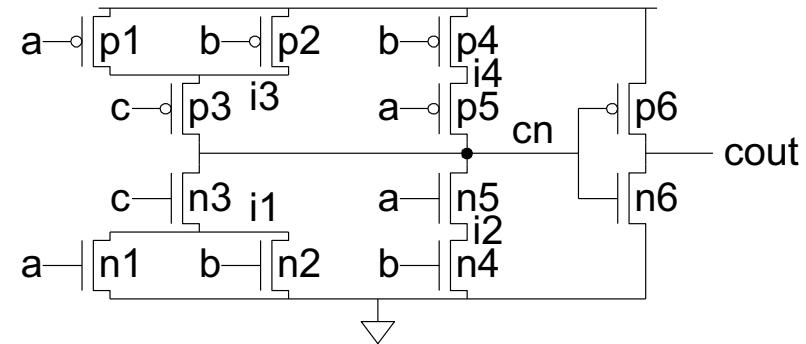
Transistor-Level Netlist

```
module carry(input a, b, c,
              output cout)

    wire      i1, i2, i3, i4, cn;

    tranif1 n1(i1, 0, a);
    tranif1 n2(i1, 0, b);
    tranif1 n3(cn, i1, c);
    tranif1 n4(i2, 0, b);
    tranif1 n5(cn, i2, a);
    tranif0 p1(i3, 1, a);
    tranif0 p2(i3, 1, b);
    tranif0 p3(cn, i3, c);
    tranif0 p4(i4, 1, b);
    tranif0 p5(cn, i4, a);
    tranif1 n6(cout, 0, cn);
    tranif0 p6(cout, 1, cn);

endmodule
```



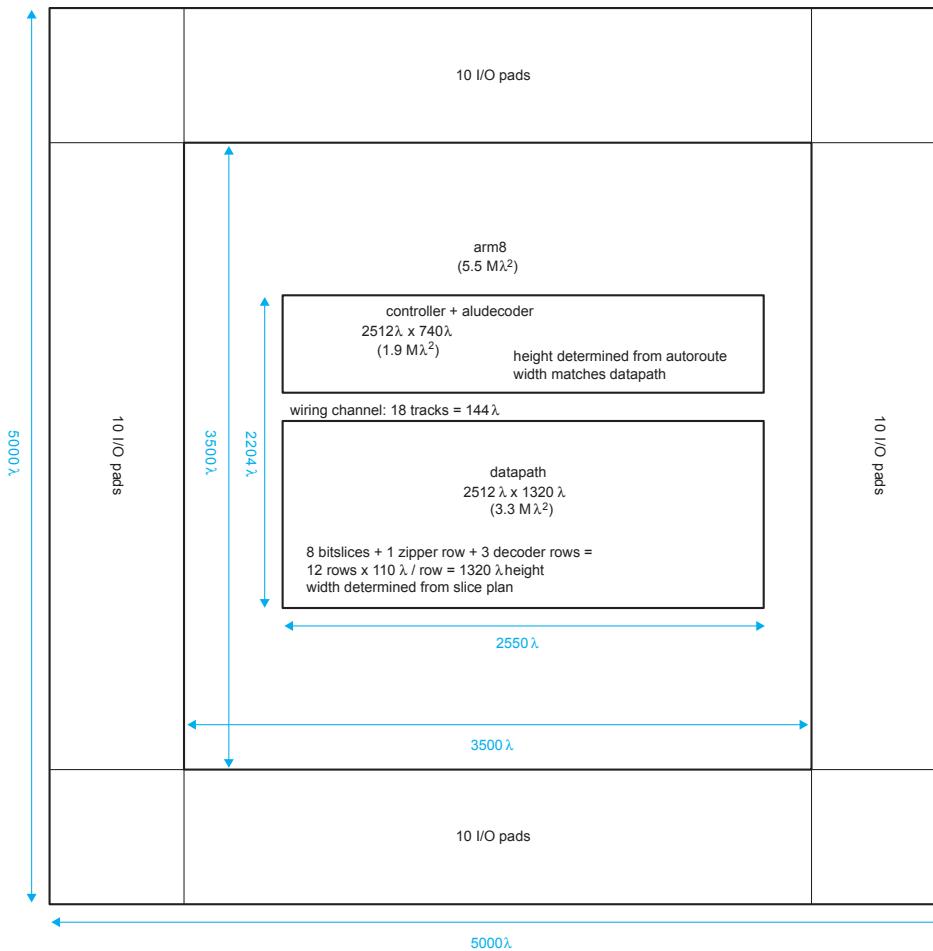
SPICE Netlist

```
.SUBCKT CARRY A B C COUT VDD GND
MN1 I1 A GND GND NMOS W=1U L=0.18U AD=0.3P AS=0.5P
MN2 I1 B GND GND NMOS W=1U L=0.18U AD=0.3P AS=0.5P
MN3 CN C I1 GND NMOS W=1U L=0.18U AD=0.5P AS=0.5P
MN4 I2 B GND GND NMOS W=1U L=0.18U AD=0.15P AS=0.5P
MN5 CN A I2 GND NMOS W=1U L=0.18U AD=0.5P AS=0.15P
MP1 I3 A VDD VDD PMOS W=2U L=0.18U AD=0.6P AS=1P
MP2 I3 B VDD VDD PMOS W=2U L=0.18U AD=0.6P AS=1P
MP3 CN C I3 VDD PMOS W=2U L=0.18U AD=1P AS=1P
MP4 I4 B VDD VDD PMOS W=2U L=0.18U AD=0.3P AS=1P
MP5 CN A I4 VDD PMOS W=2U L=0.18U AD=1P AS=0.3P
MN6 COUT CN GND GND NMOS W=2U L=0.18U AD=1P AS=1P
MP6 COUT CN VDD VDD PMOS W=4U L=0.18U AD=2P AS=2P
CI1 I1 GND 2FF
CI3 I3 GND 3FF
CA A GND 4FF
CB B GND 4FF
CC C GND 2FF
CCN CN GND 4FF
CCOUT COUT GND 2FF
.ENDS
```

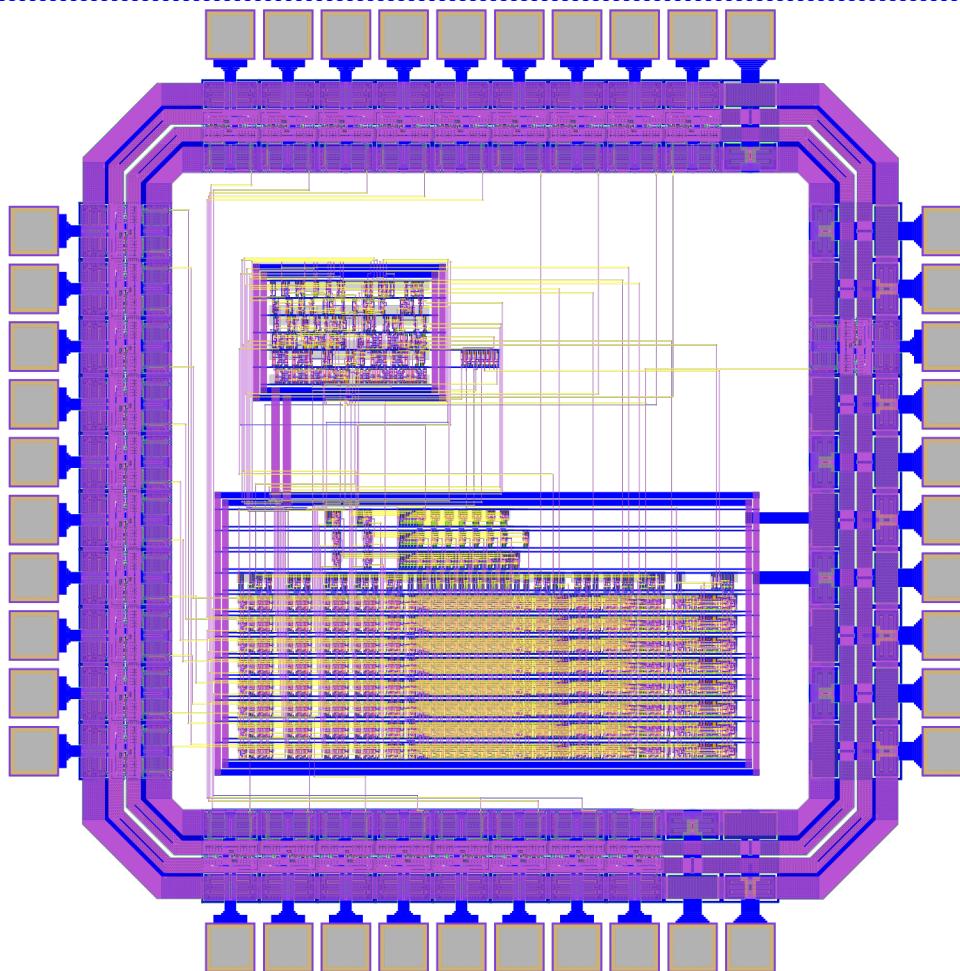
Physical Design

- Floorplan
- Standard cells
 - Place & route
- Datapaths
 - Slice planning
- Area estimation

ARM Floorplan

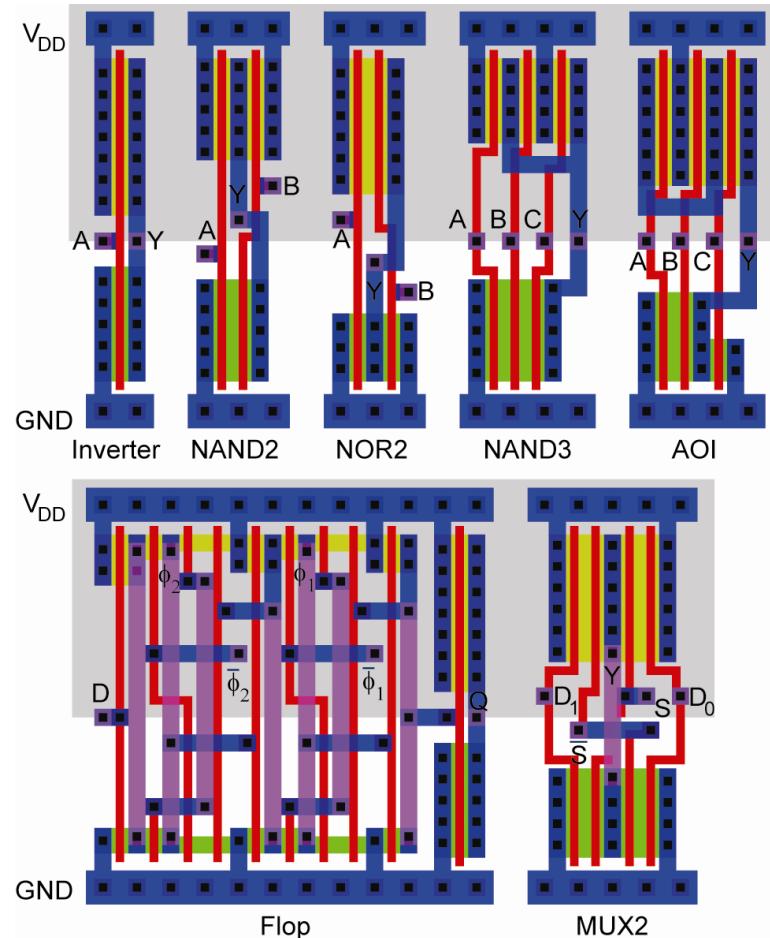


ARM Layout



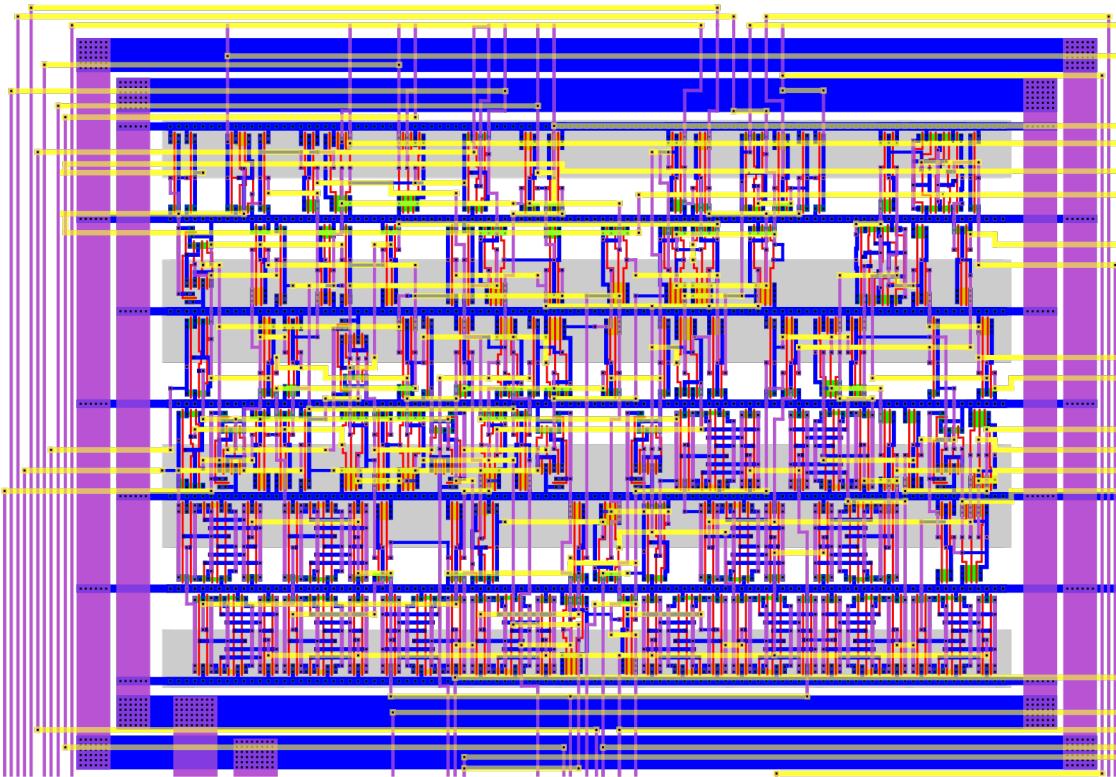
Standard Cells

- Uniform cell height
- Uniform well height
- M1 V_{DD} and GND rails
- M2 Access to I/Os
- Well / substrate taps
- Exploits regularity



Synthesized Controller

- Synthesize HDL into gate-level netlist
- Place & Route using standard cell library



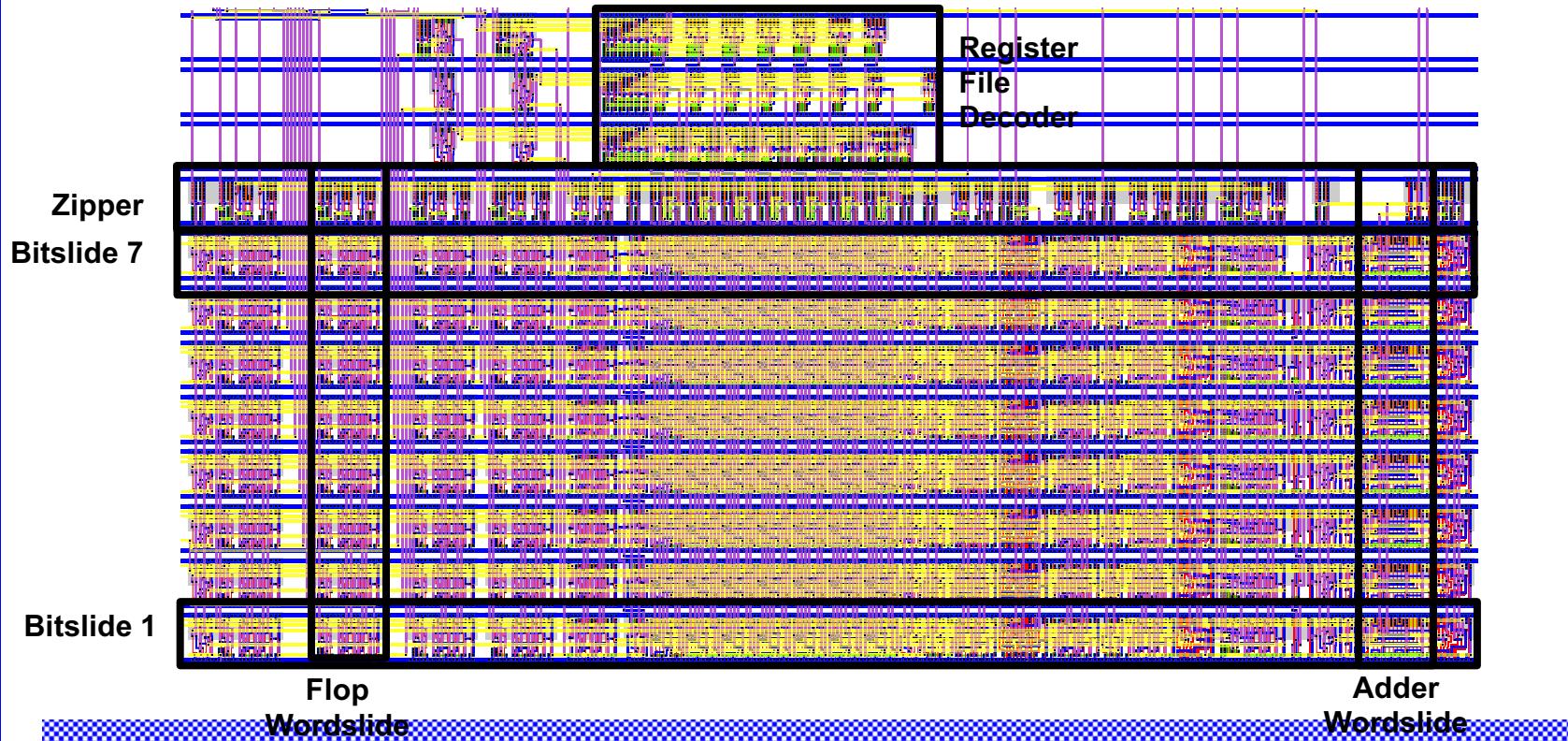
Pitch Matching

- Synthesized controller area is mostly wires
 - Design is smaller if wires run through/over cells
 - Smaller = faster, lower power as well!
- Design snap-together cells for datapaths and arrays
 - Plan wires into cells
 - Connect by abutment
 - Exploits locality
 - Takes lots of effort

A	A	A	A	B
A	A	A	A	B
A	A	A	A	B
A	A	A	A	B
C		C		D

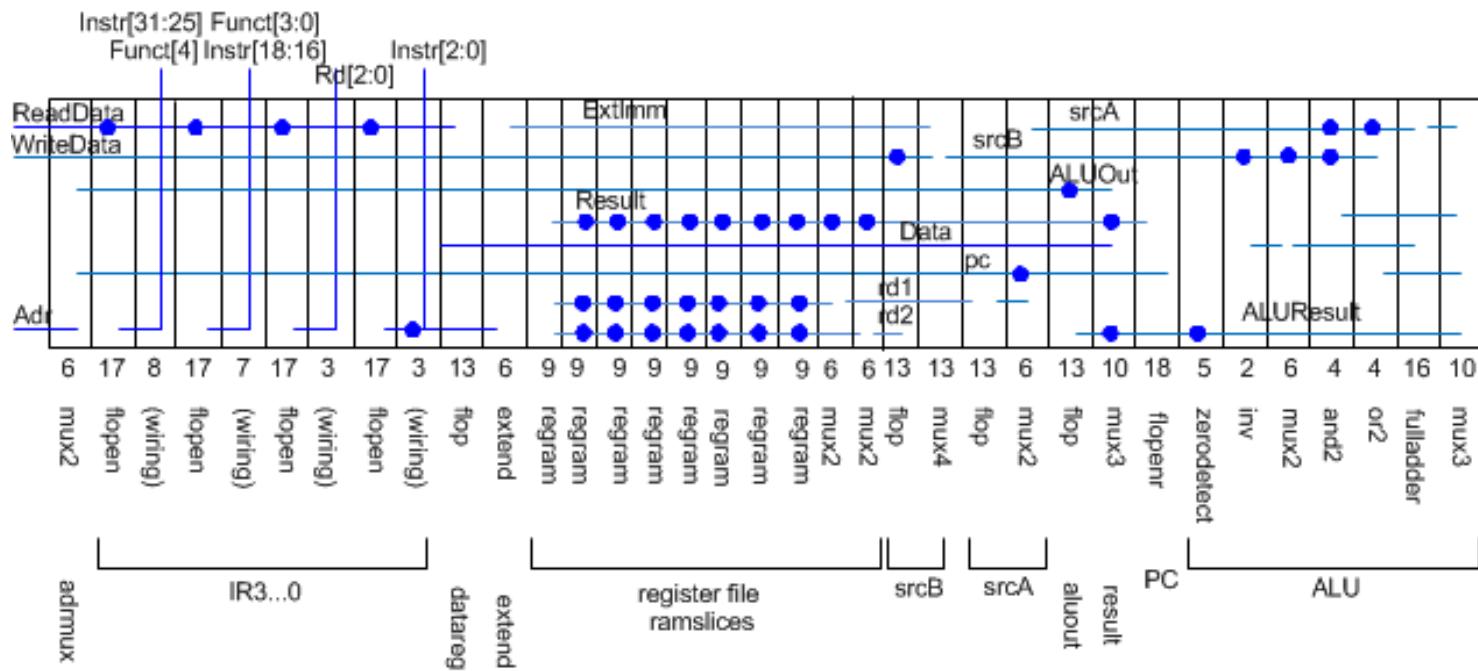
ARM Datapath

- 8-bit datapath built from wordlices
- Zipper at top drives control signals to datapath



Slice Plans

- Slice plan for bitslice
 - Cell ordering, dimensions, wiring tracks
 - Arrange cells for wiring locality



Area Estimation

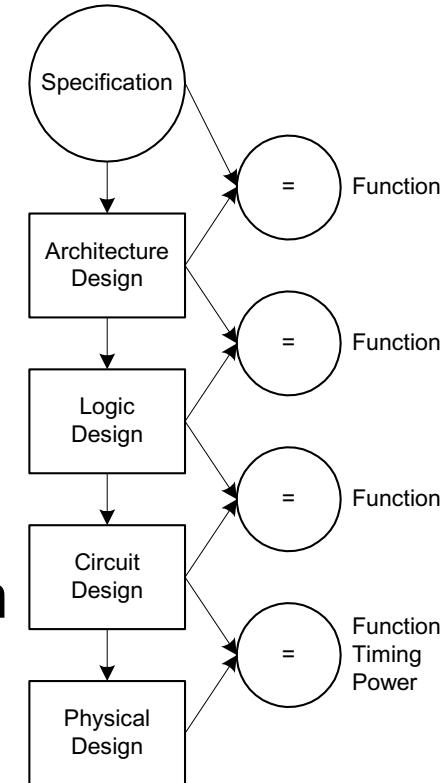
- Need area estimates to make floorplan
 - Compare to another block you already designed
 - Or estimate from transistor counts
 - Budget room for large wiring tracks
 - Your mileage may vary; derate by 2x for class.

Table 1.10 Typical layout densities

Element	Area
random logic (2-level metal process)	$1000 - 1500 \lambda^2$ / transistor
datapath	$250 - 750 \lambda^2$ / transistor or $6 \text{ WL} + 360 \lambda^2$ / transistor
SRAM	$1000 \lambda^2$ / bit
DRAM (in a DRAM process)	$100 \lambda^2$ / bit
ROM	$100 \lambda^2$ / bit

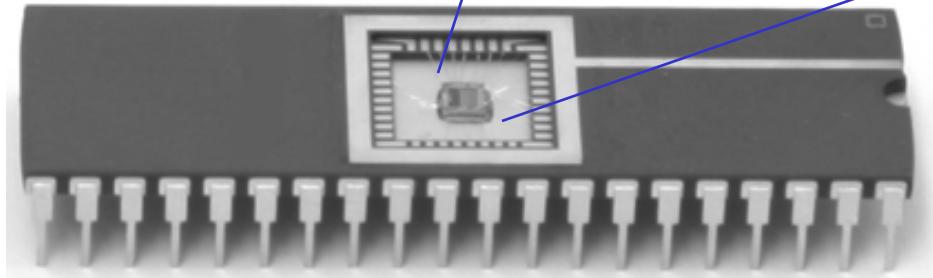
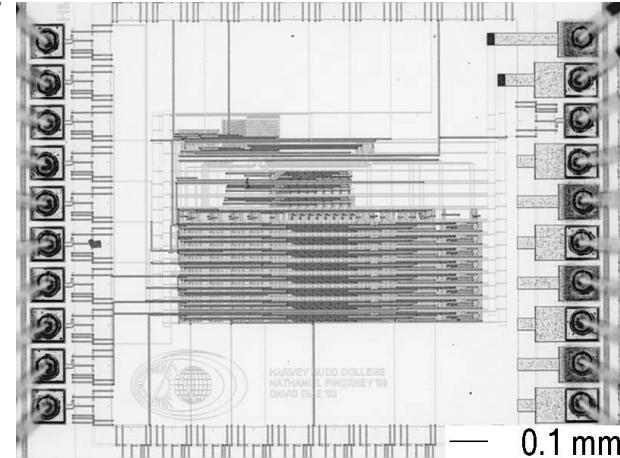
Design Verification

- ❑ Fabrication is slow & expensive
 - MOSIS 0.6μm: \$1000, 3 months
 - 65 nm: \$3M, 1 month
- ❑ Debugging chips is very hard
 - Limited visibility into operation
- ❑ Prove design is right before building!
 - Logic simulation
 - Ckt. simulation / formal verification
 - Layout vs. schematic comparison
 - Design & electrical rule checks
- ❑ Verification is > 50% of effort on most chips!



Fabrication & Packaging

- Tapeout final layout
- Fabrication
 - 6, 8, 12" wafers
 - Optimized for throughput, not latency (10 weeks!)
 - Cut into individual dice
- Packaging
 - Bond gold wires from die I/O pads to package



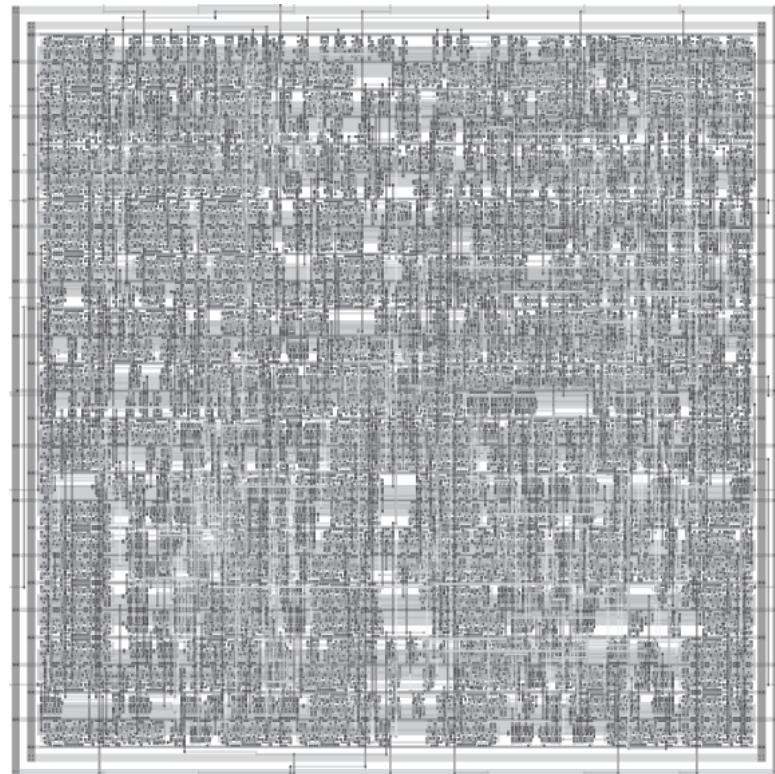
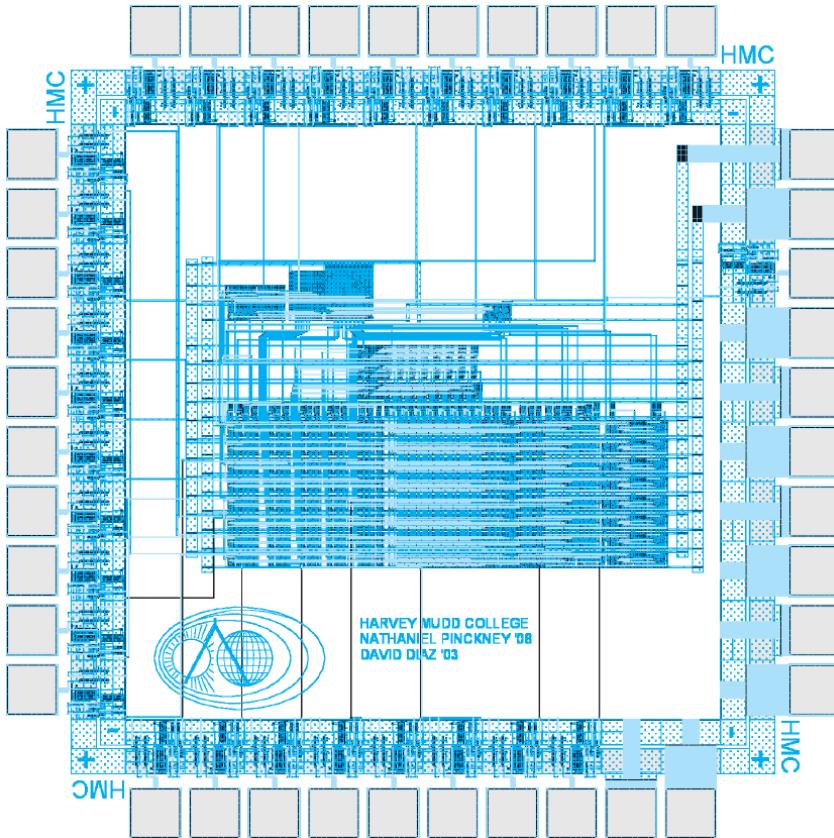
Testing



- Test that chip operates
 - Design errors
 - Manufacturing errors
- A single dust particle or wafer defect kills a die
 - Yields from 90% to < 10%
 - Depends on die size, maturity of process
 - Test each part before shipping to customer

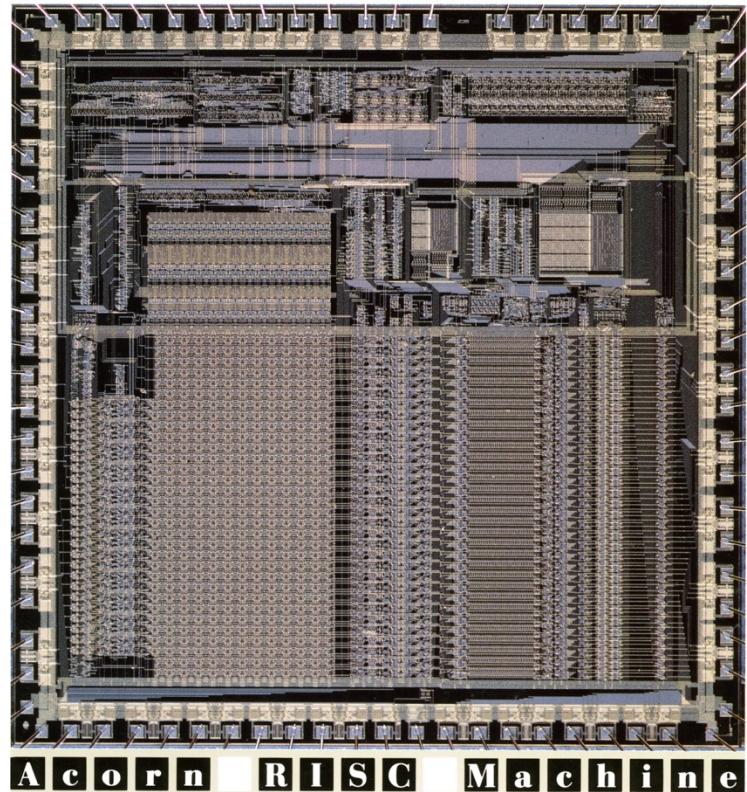
Custom vs. Synthesis

□ 8-bit Implementations



ARM1 Processor

- ❑ 1st generation ARM chip (1985)
- ❑ 24,800 transistors
- ❑ 3-stage pipeline
- ❑ 8 MHz
- ❑ 3 μ m process
- ❑ 49 mm²
- ❑ 82-pin PLCC package
- ❑ Average power = 0.1 W
- ❑ 2-phase nonoverlapping clocks
- ❑ Built for Acorn Computer



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